Title: METHOD FOR PECVD DEPOSITION OF SELECTED MATERIAL FILMS

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-36. (Canceled)

- 37. (Currently Amended) An atmosphere for a chemical vapor deposition process, comprising:
 - a deposition gas having a chemical reactability with a reactant gas; and
- a chemically inert reactability increaser reaction promoter mixed with said deposition gas at a rate of about 0.4 to 0.6 of a rate of flow of the reactant gas to form a high density plasma at a total pressure of greater than 1 millitorr.
- 38. (Currently Amended) The atmosphere of claim 37 wherein said deposition gas is a film precursor deposition gas <u>having a flow rate of greater than 10 sccm</u>.
- 39. (Currently Amended) The atmosphere of claim 37 wherein said deposition gas is a metal film precursor deposition gas, the reactant gas includes hydrogen at a flow rate of about 10,000 sccm, and the reaction promoter includes argon at a flow rate of at least 4,000 sccm.

Claims 40-66. (Canceled)